

ABSTRACT OF THE DISCLOSURE

5 A system for inspecting a component, such as a die
formed on a silicon wafer, is provided. The system includes
a two dimensional inspection system that can locate one or
more features, such as bump contacts on the die, and which
can also generate feature coordinate data. The system also
includes a three dimensional inspection system that is
10 connected to the two dimensional inspection system, such as
through an operating system of a processor. The three
dimensional inspection system receives the feature
coordinate data and generates inspection control data.

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